

HVD369B

Variable Capacitance Diode for VCO

REJ03G0502-0200 Rev.2.00 Jan 31, 2006

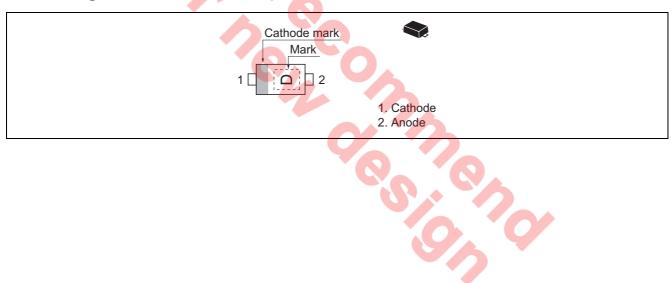
Features

- Low capacitance and to be usable at GHz.
- High capacitance ratio. (n = 2.3 min)
- Low series resistance. $(r_s = 0.5 \Omega \text{ max})$
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code	
HVD369B	D	SFP	PUSF0002ZB-A	

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V _R	15	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Electrical Characteristics

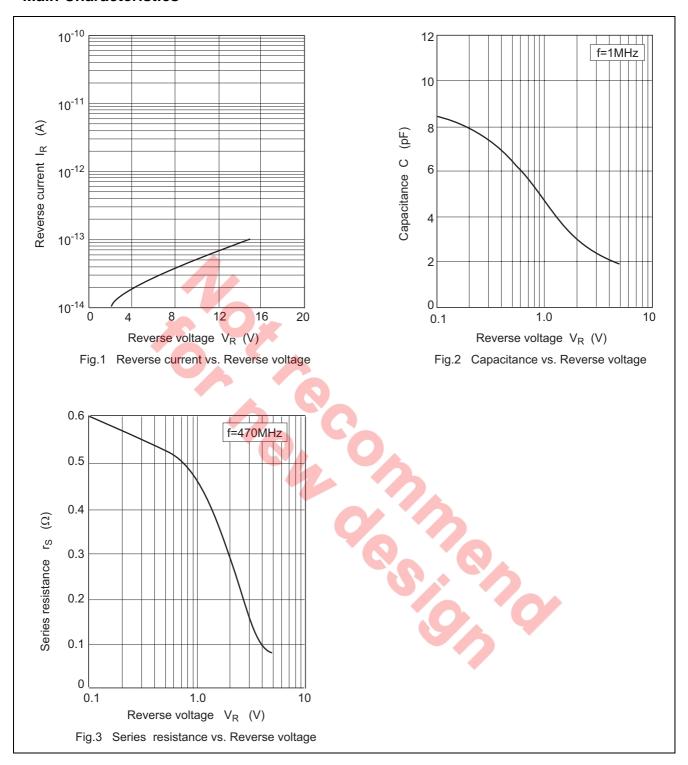
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_	_	10	nA	V _R =15 V
	I _{R2}	_	_	100		V _R = 15 V, Ta = 60°C
Capacitance	C ₁	4.65	_	5.15	pF	V _R = 1 V, f = 1 MHz
	C ₄	1.85	_	2.15		V _R = 4 V, f = 1 MHz
Capacitance ratio	n	2.30	_	_	_	C ₁ / C ₄
Series resistance	r _S		_	0.50	Ω	V _R = 1 V, f = 470 MHz

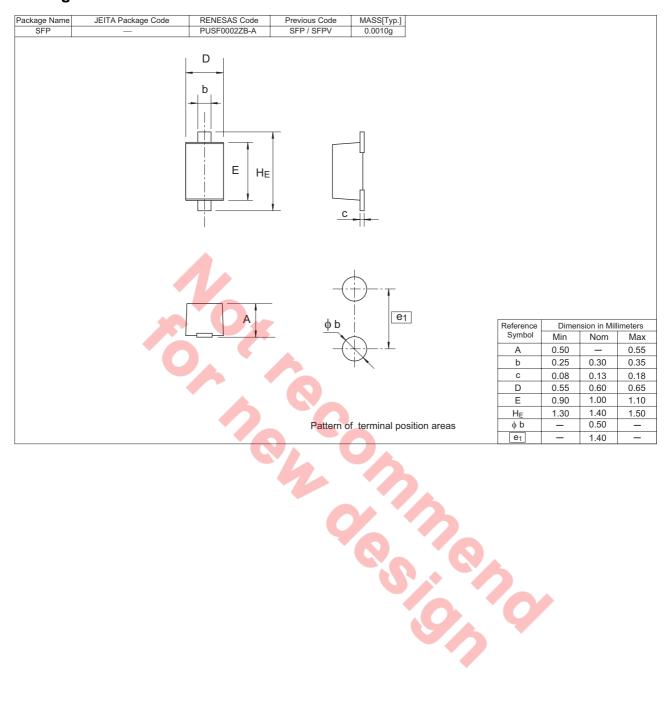
Note: For SFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.



Main Characteristics



Package Dimensions



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